

LTM8064 108LD BGA-PBF 16mm X 11.9mm X 4.92mm (TABLE OF MATERIAL DECLARATION)

**This Package is RoHS compliant per EU RoHS Directive 2003/95/EC.
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+)
polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)**

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1927	Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2 *non-disclosure	0.03293	17.09
				Continuous Filament Fiber Glass	65997-17-3	0.02920	15.16
				Copper Metal	7440-50-8	0.10939	56.77
				Zinc	7440-66-6	0.00001	0.01
				Chromium(III) oxide	1308-38-9	0.00001	0.00
				Epoxy Resin	*non-disclosure	0.00003	0.02
				Barium Compounds	7727-43-7	0.00597	3.10
				Silica amorphous	7631-86-9	0.00012	0.06
				Calcium carbonate	471-34-1	0.00001	0.00
				Amine compounds	*non-disclosure	0.00009	0.05
				Leveling agent and others	*non-disclosure	0.00026	0.14
				Acrylic Resin	*non-disclosure	0.01137	5.90
				Copper Compounds	147-14-8	0.00005	0.03
				Talc;not containing fibers like asbestos	14807-96-6	0.00069	0.36
				Aromatic carbonyl compounds	non-disclosure	0.00065	0.34
				Cyanoguanidine	461-58-5	0.00002	0.01
				Nickel	7440-02-0	0.00154	0.80
				Gold	7440-57-5	0.00033	0.17
				**Ecotoxic substances	7440-38-2 7440-28-0	0.00003	0.02
2	Solder Paste	Alloy	0.0146	Tin (Sn)	7440-31-5	0.01392	95.00
				Antimony (Sb)	7440-36-0	0.00073	5.00
3	Components	Passive/Active	0.7826	Iron Powder (Fe)	7439-89-6	0.57524	73.51
				Copper (Cu)	7440-50-8	0.15671	20.02
				Nickel (Ni)	7440-02-0	0.00607	0.78
				Tin (Sn)	7440-31-5	0.00601	0.77
				Ceramic (Ba) Compounds	12047-27-7	0.03855	4.93
4	Active Ics	Silicon	0.0101	Silicon (Si)	7440-21-3	0.01009	100.00
5	Wire	Gold	0.0019	Gold (Au)	7440-57-5	0.00188	99.99
6	Solder Ball	Alloy	0.1815	Tin (Sn)	7440-31-5	0.17511	96.50
				Silver (Ag)	7440-22-4	0.00544	3.00
				Copper (Cu)	7440-50-8	0.00091	0.50
7	Encapsulation	Epoxy Resin	1.2534	Fused Silica	60676-86-0	0.96759	77.20
				Epoxy Resin	non-disclosure	0.11155	8.90
				Phenol Resin	non-disclosure	0.11155	8.90
				Crytalline Silica	14808-60-7	0.03760	3.00
				Carbon Black	1333-86-4	0.00627	0.50
				Metal Hydroxide	non-disclosure	0.01880	1.50
Total Package Weight			2.4367				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts